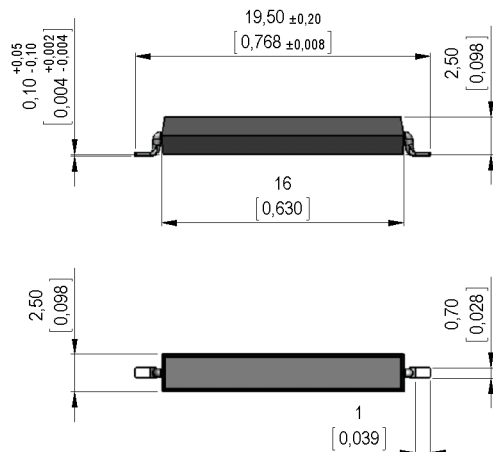




Dimensions mm[inch]

tolerances according to DIN ISO 2768-m
Toleranzen gem. DIN ISO 2768-m



Isometric

Scale 2:1
Maßstab 2:1

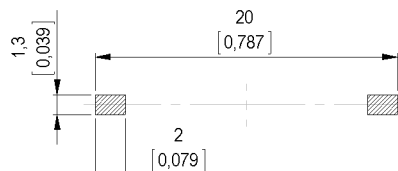


Marking

according to EN60062/factory code
gem. EN60062/Fertigungsstätte

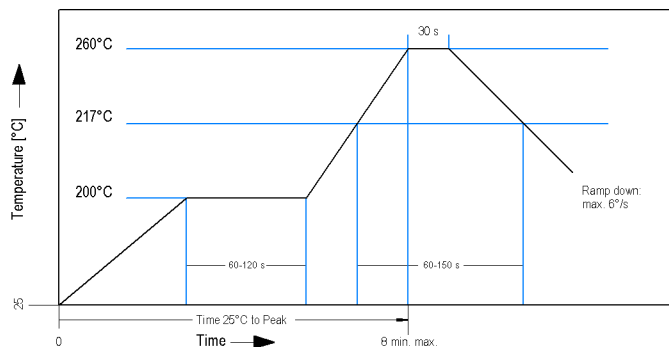


Recommended PCB Pad Layout

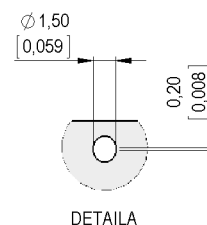
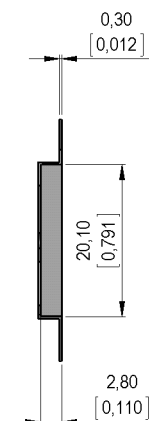
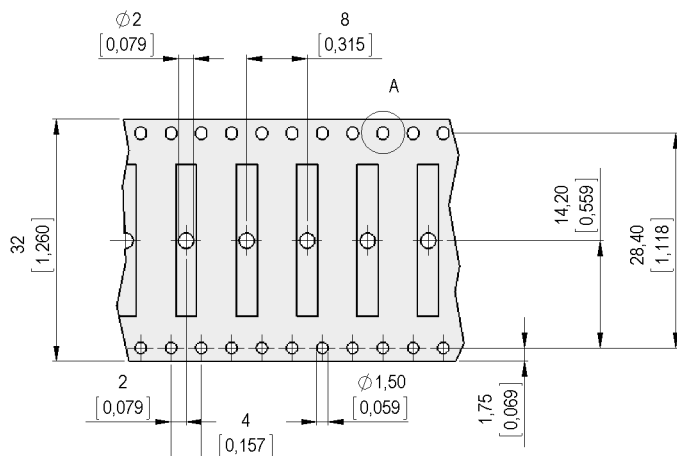


Solder Reflow Profile

reflow soldering conditions according to JEDEC norm J-STD 020D.1



Packaging



Magnetic properties	Conditions	Min	Typ	Max	Unit
Pull-In	at 20°C	45,2		80,6	AT
Test equipment		KMS-11			
Pull-In in milliTesla (modified conta	MS150 - phys. caused tolerance +/- 0,1mT	2,5		3,5	mT
Test equipment		MS-150			

Contact data 66/1	Conditions	Min	Typ	Max	Unit
Contact-material		Rhodium			
Contact rating	Any DC combination of V & A not to exceed their individual max.'s			10	W
Switching voltage	DC or Peak AC			180	VDC
Switching current	DC or Peak AC			0,5	A
Carry current	DC or Peak AC			1,25	A
Contact resistance static	Measured with 40% overdrive Start Value			150	mOhm
Breakdown voltage (>20 AT)	according to IEC 255-5	200			VDC

Special Product Data	Conditions	Min	Typ	Max	Unit
Housing material		epoxy resin			
Approval		UL- File-Nr. E156887			

Environmental data	Conditions	Min	Typ	Max	Unit
Shock	1/2 sine wave duration 11ms			30	g
Vibration	from 10 - 2000 Hz			20	g
Operating temperature		-40		130	°C
Storage temperature		-50		130	°C
Soldering Temperature Tsold	Reflow acc.IPC/JEDEC J-STD-020D.1			260	°C
Washability		fully sealed			

General data	Conditions	Min	Typ	Max	Unit
Component marking	general descripton	MEDER E YM/P			